



GooLED

GooLED-LG-4830 Pin Fin Heat Sink Φ 48mm for LG Innotech

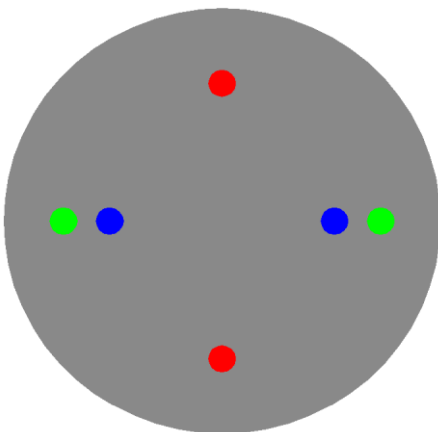
Features VS Benefits

- * The GooLED-LG-4830 LG Innotech Pin Fin LED Heat Sinks are specifically designed for luminaires using the LG Innotech LED engines.
- * Mechanical compatibility with direct mounting of the LED engines to the LED cooler and thermal performance matching the lumen packages.
- * For spotlight and downlight designs from 400 to 1,300 lumen.
- * Thermal resistance range R_{th} 6.25°C/W.
- * Modular design with mounting holes foreseen for direct mounting of LG Innotech COB series.
- * Diameter 48.0mm - standard height 30.0mm Other heights on request.
- * Forged from highly conductive aluminum.



Zhaga LED engine and radiator assembly is a unified future international standardization

- * Below you find an overview of LG Innotech COB's and LED modules which standard fit on the Pin Fin LED Heat Sinks.
- * In this way mechanical after work and related costs can be avoided, and lighting designers can standardize their designs on a limited number of LED Pin Fin LED Heat Sink.



LG Innotech LED Modules directly Mounting Options

LG Innotech 7W&10W COB series.

LEMWM19480xxxxxx;
LEMWM19490xxxxxx;
LEMWM19680xxxxxx;
LEMWM19690xxxxxx;

With the Zhaga Book 3 holders for the green indicator marks.
TE Connectivity Holder: 2213382-1;
Without the holders for the blue indicator marks.
Direct mounting with machine screws M3x6.5mm.

LG Innotech 16W&21W COB series.

LEMWM24780xxxxxx;
LEMWM24790xxxxxx;
LEMWM24980xxxxxx;
LEMWM24990xxxxxx;

With the Zhaga Book 3 holders for the green indicator marks.
TE Connectivity Holder: 2213130-1;
BJB Holder: 47.319.2011.50;
Without the holders for the red indicator marks.
Direct mounting with machine screws M3x6.5mm.



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Mounting Options and Drawings & Dimensions

Example:GooLED-LG-4830-B-1,2

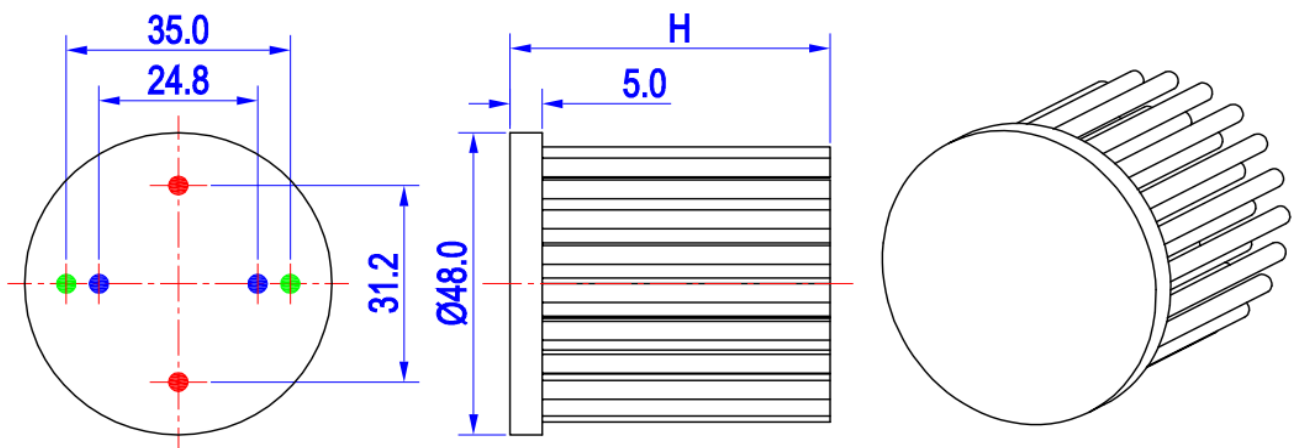
Example:GooLED-LG-48 **1** - **2** - **3**

- 1** Height (mm)
- 2** Anodising Color
B-Black
C-Clear
Z-Custom
- 3** Mounting Options - see graphics for details Combinations available
Ex.order code - 12
means option 1 and 2 combined

Notes:

- Mentioned models are an extraction of full product range.
- For specific mechanical adaptations please contact MingfaTech.
- MingfaTech reserves the right to change products or specifications without prior notice.

MOUNTING OPTION	Module type	Holder NO.	THREAD	THREAD DEPTH	THREAD HOLE DISTANCE
1	7W&10W COB	/	M3	6.5mm	24.8mm/ 2-@180°
2		/	M3	6.5mm	31.2mm/ 2-@180°
3	16W&21W COB	BJB Holder 47.319.2011.50	M3	6.5mm	35.0mm/ 2-@180° (Zhaga Book 3)
		TE Holder 2213130-1			
	7W&10W COB	TE Holder 2213382-1			



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The product data table

	Model No.	GooLED-LG-4830
	Heatsink Size	Φ48xH30mm
	Heatsink Material	AL1070
	Finish	Black Anodized
	Weight (g)	46.0
	Dissipated power (T_{hs-amb},50°C)	8.0 (W)
	Cooling surface area (mm²)	15420
	Thermal Resistance (R_{hs-amb})	6.25 (°C/W)

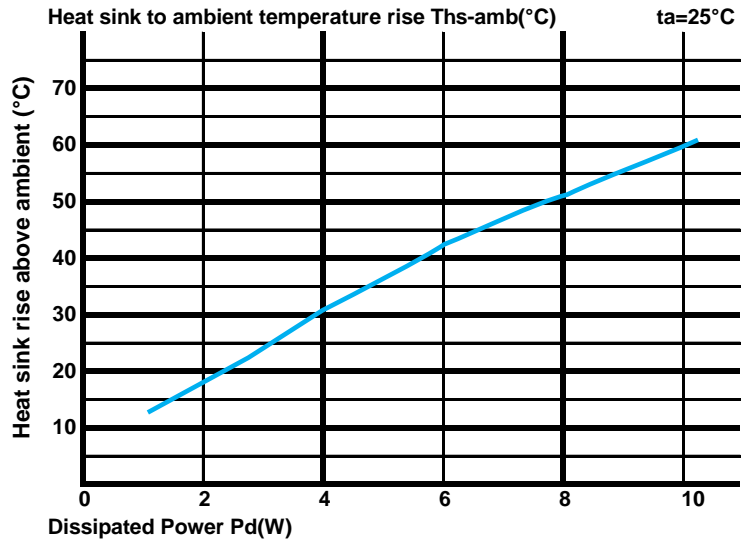
The thermal data table

* Please be aware the dissipated power Pd is not the same as the electrical power Pe of a LED module.

*To calculate the dissipated power please use the following formula: Pd = Pe x (1-ηL).

Pd - Dissipated power ; Pe - Electrical power ; ηL = Light efficiency of the LED module;

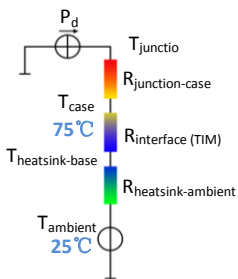
Dissipated Power Pd(W)	Heat sink to ambient thermal resistance R _{hs-amb} (°C/W)		Heat sink to ambient temperature rise T _{hs-amb} (°C)	
	GooLED-LG-4830			
2.0	9.00	18.0		
4.0	7.50	30.0		
6.0	7.00	42.0		
8.0	6.25	50.0		
10.0	5.90	59.0		



*The aluminum substrate side of the package outer shell is thermally connected to the heat sink via TIM (Thermal interface material).

MingFa recommends the use of a high thermal conductive interface between the LED module and the LED cooler.

Either thermal grease, A thermal pad or a phase change thermal pad thickness 0.1-0.15mm is recommended.



*Thermal resistance is a heat property and a measurement of a temperature difference by which an object or material resists a heat flow.

Geometric shapes are different, the thermal resistance is different. Formula: $\theta = (T_{hs} - T_a) / P_d$

θ - Thermal Resistance [°C/W]; T_{hs} - Heatsink temperature; T_a - Ambient temperature;

*The thermal resistance between the junction section of the light-emitting diode and the aluminum substrate side of the package outer shell is R_{junction-case}, the thermal resistance of the TIM outside the package is R_{interface (TIM)} [°C/W], the thermal resistance with the heat sink is R_{heatsink-ambient} [°C/W], and the ambient temperature is T_{ambient} [°C].

*Thermal resistances outside the package R_{interface (TIM)} and R_{heatsink-ambient} can be integrated into the thermal resistance R_{case-ambient} at this point. Thus, the following formula is also used:

$$T_{junction} = (R_{junction-case} + R_{case-ambient}) \cdot P_d + T_{ambient}$$